

ABSTRACT OF THE DISCLOSURE

In an electronic circuit equipment using a multilayer circuit board on which a semiconductor chip is mounted, a thin film capacitor is provided on the multilayer circuit board. Moreover, a first electrode of the thin film capacitor and a first wiring of the multilayer circuit board are electrically connected to each other, and a second electrode of the thin film capacitor and a second wiring of the multilayer circuit board are electrically connected to each other, respectively. Furthermore, a thin film dielectric of the thin film capacitor was grown epitaxially with the first electrode as its base. The employment of the multilayer circuit board makes it possible to provide the electronic circuit equipment using the multilayer circuit board that includes the built-in thin film capacitor having the high dielectric-constant thin film dielectric.

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